506958284 11/03/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOUNGSUK KIM	10/28/2021
BYEONGDECK JANG	10/26/2021
AKIHITO KAWAI	10/20/2021
SHUNSUKE TERANISHI	10/20/2021

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17453411

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SIGNATURE:	/PATRICK G. BURNS/
DATE SIGNED:	11/03/2021

Total Attachments: 5

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PATENT 506958284 REEL: 058008 FRAME: 0968

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PATENT REEL: 058008 FRAME: 0969

GREER, BURNS & CRAIN, LTD.
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Declaration and Assignment for Utility or Design Patent Application

The title of this invention is:

WAFER MANUFACTURING METHOD AND LAMINATED DEVICE CHIP MANUFACTURING METHOD

I.	Declaration
	As a below named inventor, I/we hereby declare that this declaration is directed to:
	(×) the attached application,
	OR
	() United States application or PCT international application number filed on and was amended on (MM/DD/YYYY) (if applicable).
	The above-identified application was made or authorized to be made by me.
invent	I believe that I am the original inventor or an original joint inventor of a claimed ion in the application.
punish both.	I hereby acknowledge that any willful false statement made in this declaration is nable under 18 U.S.C. \S 1001 by fine or imprisonment of not more than five (5) years, or
II.	Assignment
	(×) Check this box to assign this invention.
invent to:	FOR VALUE RECEIVED, the receipt of which is hereby acknowledged, the below named for or inventors (hereinafter called "ASSIGNOR") hereby assigns, transfers, and sets over
DISC	CO CORPORATION of 13-11, Omori-Kita 2-chome, Ota-ku, Tokyo 143-8580 Japan
(herei	nafter called "ASSIGNEE"), the full and exclusive right, title, and interest in and to the

above-named invention and all rights privileges under any Letters Patent that may be granted

thereon, including all rights, if any, to sue for past infringement.

PATENT REEL: 058008 FRAME: 0970 ASSIGNOR also assigns all rights, titles, and interests in and to said invention in all foreign countries, and all applications for Patent which may evolve therefrom, including the right to claim International Convention priority.

The ASSIGNOR agrees without charge to said ASSIGNEE but at its expense (a) to execute (i) all necessary papers to be used in connection with the above-identified application and any additional, continuing, or divisional applications, as the ASSIGNEE may deem necessary or expedient, (ii) all papers in connection with any other legal or quasi-legal proceedings relating to the above-identified application or any additional, continuing, or divisional application thereof; (b) to cooperate with ASSIGNEE in every way possible in obtaining evidence and going forward in any such proceedings; and (c) to perform all other affirmative acts which may be necessary or desirable to obtain a grant of a valid patent.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States to issue any and all Letters Patent that may be granted upon the above-identified application or any additional, continuing or divisional applications thereof to the ASSIGNEE, its successors and assigns.

ASSIGNOR hereby covenants and warrants that he or she has full right to convey the entire right, title and interest by this instrument, free of any encumbrances and that no other agreement has been or will be executed in conflict herewith.

I. Inventor Signatures

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T20-016

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RECORDED: 11/03/2021